WHAT IS CLAIMED IS:

1. A method for manufacturing a flexible panel comprising:

(a) providing a first substrate having a plurality of functional switches or conducting lines thereon;

(b) bonding a second substrate on said plurality of functional switches or conducting lines;

(c) thinning said first substrate to a predetermined thickness;

(d) adhering or sealing a flexible third substrate on said first substrate, wherein said first substrate is sandwiched between said second substrate and said third substrate; and

(e) removing said second substrate.

2. The method as claimed in claim 1, further comprising a step (f) of forming a plurality of light valves, light-emitters, or conducting layers on said plurality of switches or conducting lines, and adhering or sealing a flexible fourth substrate on said plurality of light valves, light-emitters, or conducting layers after said step (e), wherein said plurality of light valves, light-emitters, or conducting layers are located between said third substrate and said fourth substrate.

3. The method as claimed in claim 1, wherein said first substrate is a glass substrate.

4. The method as claimed in claim 1, wherein said thinning method in step (c) is polishing, cutting, or etching.

5. The method as claimed in claim 1, wherein said switch is a thin film transistor.

6. The method as claimed in claim 1, wherein said first substrate is thinned to have a thickness ranging from 30 to 100 μm.

7. The method as claimed in claim 1, wherein said flexible third substrate is made of plastic.

8. A method for manufacturing a flexible panel comprising:

(a) providing a first substrate having a plurality of functional switches or conducting lines thereon;

(b) forming a plurality of light valves, light-emitters, or conducting layers on said plurality of switches or conducting lines;

(c) adhering or sealing a flexible third substrate on said plurality of light valves, light-emitters, or conducting layers;

(d) thinning said first substrate to a predetermined thickness; and

(e) bonding a flexible fourth substrate on said thinned first substrate, wherein said first substrate, said plurality of light valves, light-emitters, or conducting layers, and said plurality of functional switches or conducting lines are located between said third substrate and said fourth substrate.

9. The method as claimed in claim 8, wherein said first substrate is a glass substrate.

10. The method as claimed in claim 8, wherein said thinning method in step (c) is polishing, cutting, or etching.

11. The method as claimed in claim 8, wherein said switch is a thin film transistor.

12. The method as claimed in claim 8, wherein said first substrate

is thinned to have a thickness ranging from 30 to 100 μm.

13. The method as claimed in claim 8, wherein said flexible third or fourth substrate is made of plastic.

14. A method for manufacturing a flexible panel comprising:

(a) providing a first substrate having a plurality of functional switches or conducting lines thereon;

(b) bonding a second substrate on said plurality of functional switches or conducting lines;

(c) thinning said first substrate to a predetermined thickness;

(d) adhering or sealing a fifth substrate on said first substrate;

(e) removing said second substrate;

(f) forming a plurality of light valves, light-emitters, or conducting layers on said plurality of functional switches or conducting lines;

(g) removing said fifth substrate on said first substrate; and

(h) coating a flexible polymer on the surface of said plurality of light valves, light-emitters, or conducting layers and said first substrate.

15. The method as claimed in claim 14, wherein said first substrate is a glass substrate.

16. The method as claimed in claim 14, wherein said thinning method in step (c) is polishing, cutting, or etching.

17. The method as claimed in claim 14, wherein said switch is a thin film transistor.

18. The method as claimed in claim 14, wherein said first substrate

is thinned to have a thickness ranging from 30 to 100 μm.

19. The method as claimed in claim 14, wherein the coating method in step (h) is immersion or spin coating.

20. The method as claimed in claim 14, wherein the thickness of said polymer ranges from 1 to 10 μm.